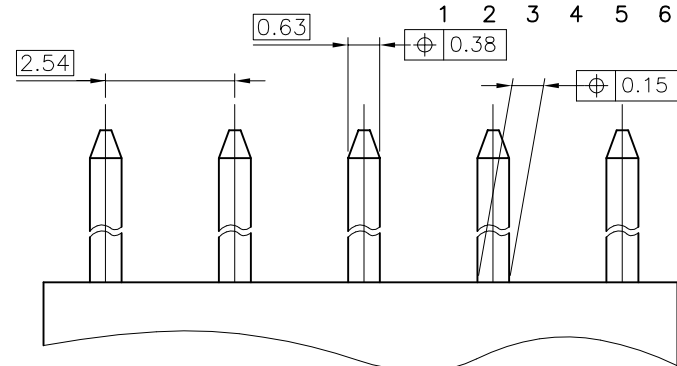
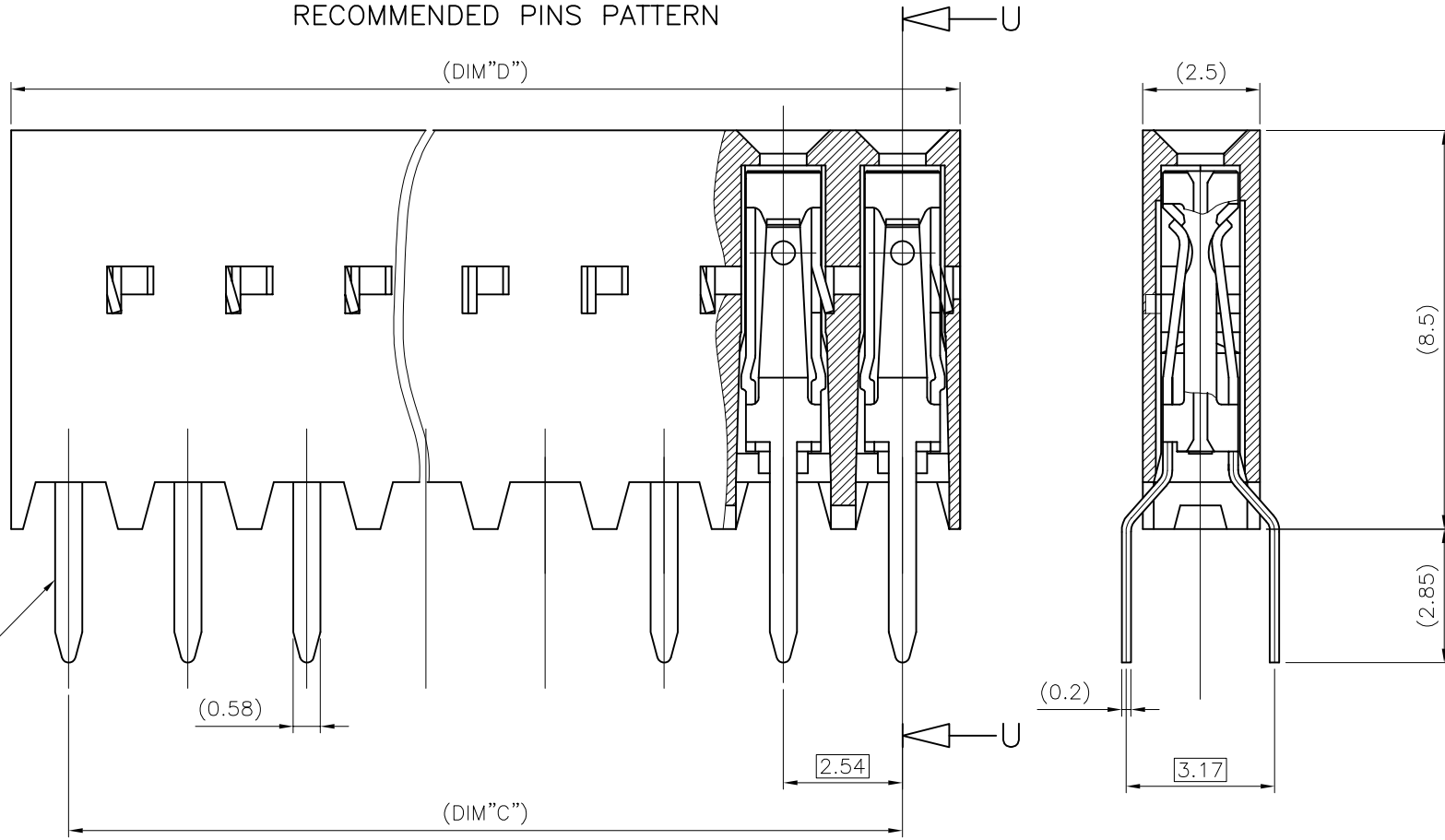


PRODUCT N°	DIM"C"	DIM"D"	CONTACT PLACED IN CAVITY																										
95200-Y01(LF)	48.26	50.72	X	X	X						X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	
95200-Y02(LF)	7.62	10.08	X		X																								
95200-Y03(LF)	53.34	55.80	X				X			X			X			X			X			X			X			X	
95200-Y04(LF)	53.34	55.80	X	X		X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X

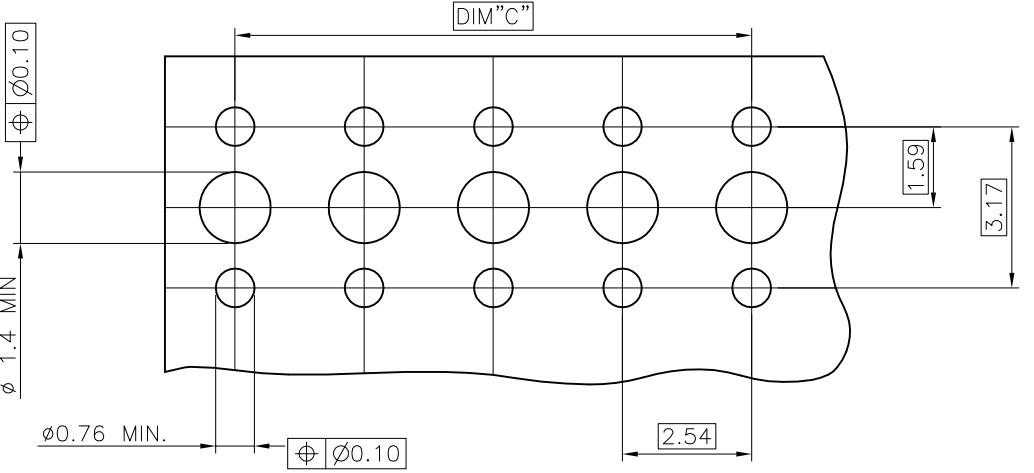
WHEN NEEDED, SUFFIX LETTER "LF" INDICATES THE PRODUCT IS RoHS COMPATIBLE, SEE NOTE 3



MINIMUM MATING PIN LENGTH: 5 mm.  
RECOMMENDED PINS PATTERN



SECTION U-U



RECOMMENDED HOLE PATTERN.

NOTES:

- MATERIAL HOUSING: THERMOPLASTIC POLYESTER, 30% GLASS FILLED, COLOUR BLUE, FLAME RETARDANT: PER UL-94 CATEGORY V0. MATERIAL TERMINAL: PHOSPHORE BRONZE EXTRA HARD.
- CONNECTOR MEANT TO BE USED FOR PC BOARD WITH NON PLATED THROUGH HOLES.
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS
  - PLATING:
    - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
  - MANUFACTURING PROCESS COMPATIBILITY
    - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
  - LABELING:
    - MEETS PACKAGING SPECS AS PER GS-14-920
  - LEGAL STATEMENT: SEE GS-22-008

95200-4XX	5 µm SnPb	SnPb
95200-3XX	0.75 µm GOLD	SnPb
PLATING CODE	CONTACT AREA	SOLDER TAIL
	PLATING THICKNESS OVER 1.27µm Ni	

95200-4XXLF	5 µm Sn	Sn
95200-3XXLF	0.76 µm GOLD	SnPb
PLATING CODE	CONTACT AREA	SOLDER TAIL
	PLATING THICKNESS OVER 1.27µm Ni	

mat'l. code	surface	tolerance	projection	product family
SEE NOTES	ISO 1302	ISO 406 ISO 1101		DX VCC SR
ltr	ecn	no	dr	date
H	F04-0347	DLE		04.11.15
J	F06-0233	DLE		06.07.13
K	F07-0271	LMU		07.12.06
		dr	D.LEGRAND	01.12.05
E	F10724	PNZ		01.12.05
F	F20337	DLE		02/05/29
G	F03-0284	DLE		03.10.15
		appd	PNZ	01.12.05
sheet index	revision	sheet		



OFF SET LEGS  
SELECTED LOADED

95200